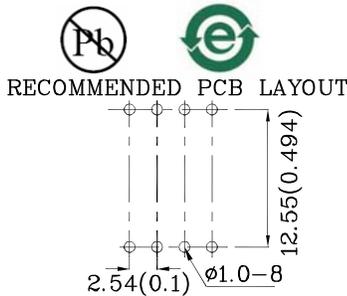
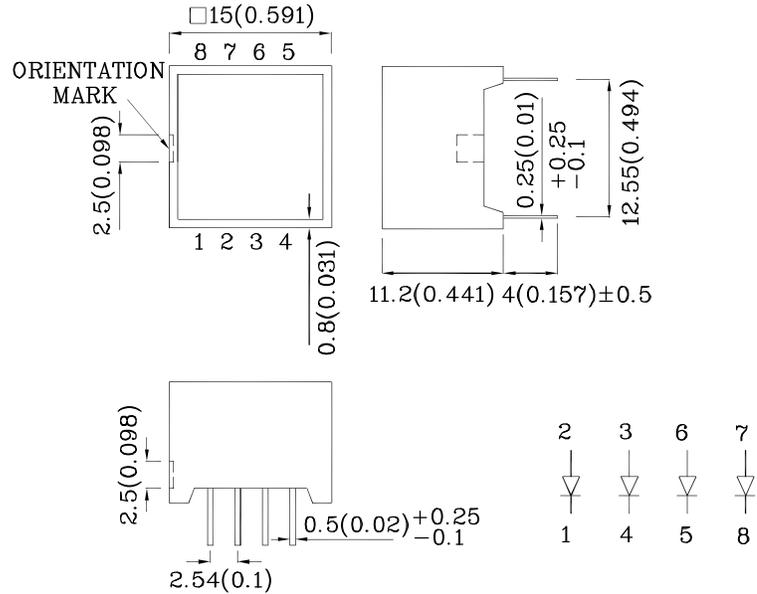


Features

- Robust package
- Uniform light disbursement
- Ideal for backlighting logos or icons
- Excellent for flush mounting
- RoHS compliant



Package Schematics



Notes:

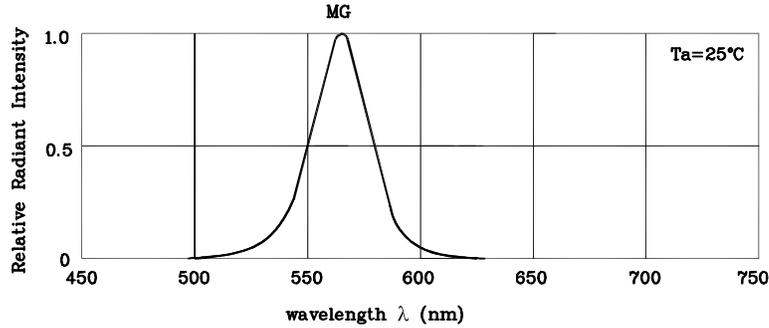
1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
2. Specifications are subject to change without notice.

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$)		MG (GaP)	Unit
Reverse Voltage	V_R	5	V
Forward Current	I_F	25	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i_{FS}	140	mA
Power Dissipation	P_D	62.5	mW
Operating Temperature	T_A	-40 ~ +85	°C
Storage Temperature	T_{stg}	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3-5 Seconds		

Operating Characteristics ($T_A=25^\circ\text{C}$)		MG (GaP)	Unit
Forward Voltage (Typ.) ($I_F=20\text{mA}$)	V_F	2.2	V
Forward Voltage (Max.) ($I_F=20\text{mA}$)	V_F	2.5	V
Reverse Current (Max.) ($V_R=5\text{V}$)	I_R	10	μA
Wavelength of Peak Emission CIE127-2007* (Typ.) ($I_F=20\text{mA}$)	λ_P	565*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) ($I_F=20\text{mA}$)	λ_D	568*	nm
Spectral Line Full Width At Half-Maximum (Typ.) ($I_F=20\text{mA}$)	$\Delta\lambda$	30	nm
Capacitance (Typ.) ($V_F=0\text{V}$, $f=1\text{MHz}$)	C	15	pF

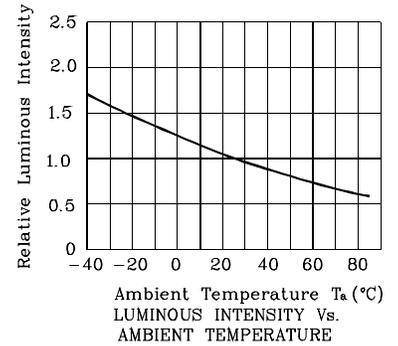
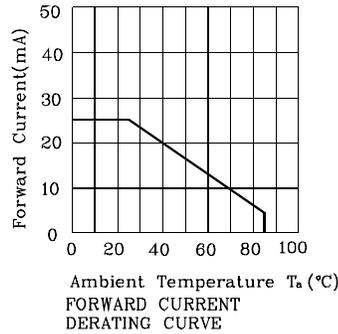
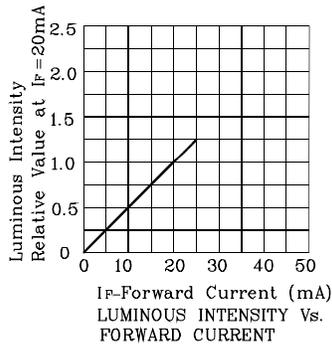
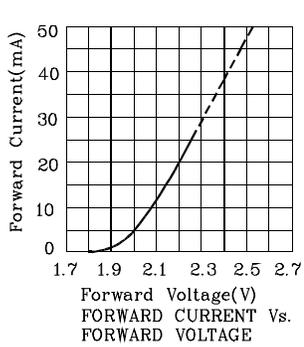
Part Number	Emitting Color	Emitting Material	Luminous Intensity CIE127-2007* ($I_F=20\text{mA}$) mcd		Wavelength CIE127-2007* nm λ_P	Lens-color
			min.	typ.		
XEMG29DX	Green	GaP	40 8*	63 20*	565*	Green Diffused

*Luminous intensity value and wavelength are in accordance with CIE127-2007

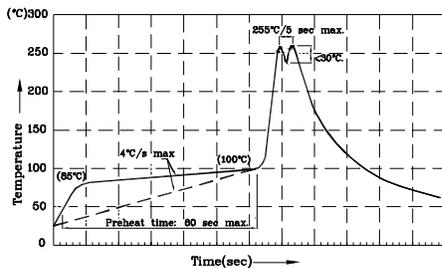


RELATIVE INTENSITY Vs. CIE WAVELENGTH

❖ MG



Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



Notes:

1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
3. Do not apply stress to the epoxy resin while the temperature is above 85°C.
4. Fixtures should not incur stress on the component when mounting and during soldering process.
5. SAC 305 solder alloy is recommended.
6. No more than one wave soldering pass.

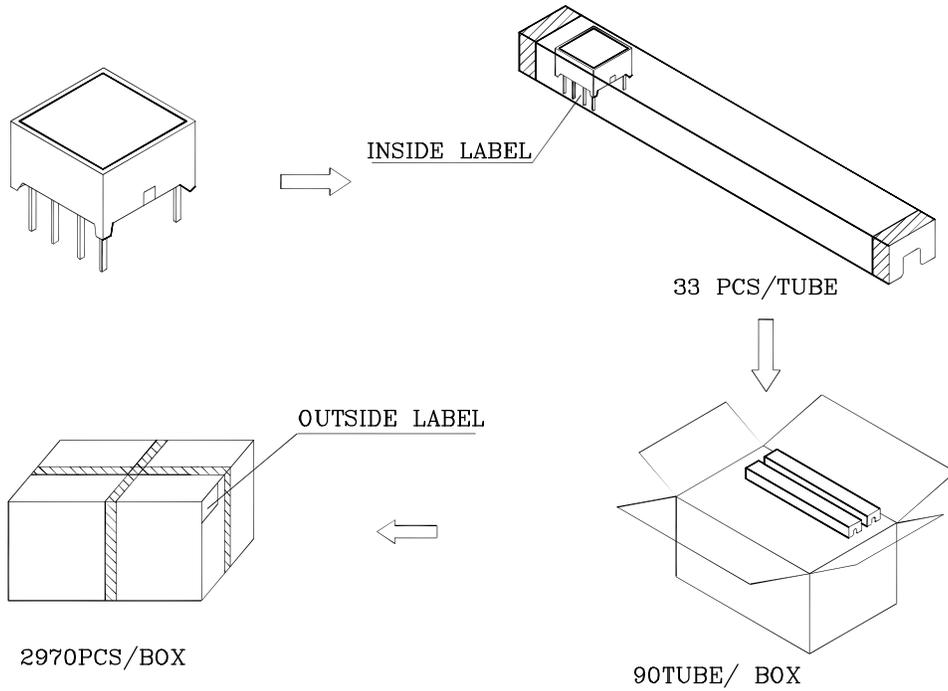
Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

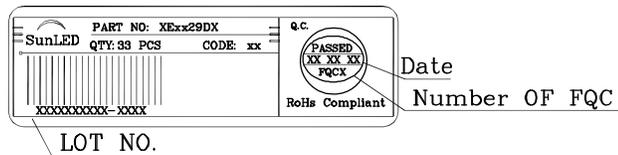
1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

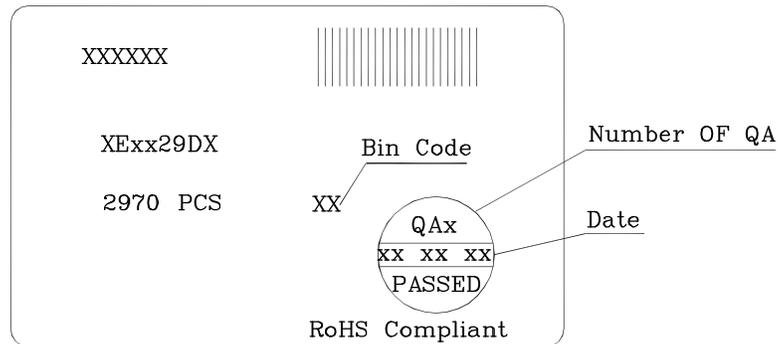
PACKING & LABEL SPECIFICATIONS



Inside Label On IC-tube



Outside Label On Box



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